

Impedance of High-Speed Traces: Specification and Consistency in Manufacturing

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The DUT

- 20-layer
- 10"x15" outline
- Many Gbps lanes
- Two separate fabricators (A and B)





The Test Procedure

- DM and CM impedances measured
- Via launch and trace-end excluded







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DesignCon 2008, February 5, 2008, Santa Clara, CA







Measured Differential Impedance vs. Trace Length (Fab. A)









Measured Differential Impedance vs. Trace Length (Fab. B)



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Layer-to-layer Consistency



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Comparing Fab. A and Fab. B



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Comparing Test Coupons

Fab. A

Fab. B



There was no test coupon built into the board The test coupon was added by the fabricators



Conclusions

After removing the outliers from the measured data, the impedance spread from layer to layer as well as over the entire board was around +-5 ohms on the 100-ohm differential traces.

The average values, however, showed a systematic eight ohms difference between the two fabricators, which was not explainable by comparing the First Article Reports from the two fabricators.

The impedance offset was due to the differences in the impedance coupons used by the two fabricators.



THANK YOU

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